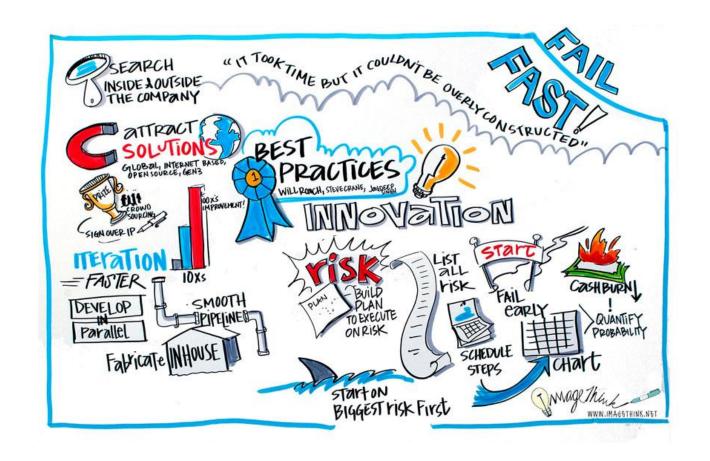




#### R&D on Experimental Technologies

# The Process

- Goals and guidelines
- Time line
- Preliminary list of R&D themes
- External teams



#### Our goals

In one year from now we should ...

- have defined a convincing and ambitious **R&D programme over 5 years**, which covers the most

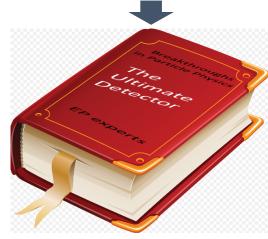
100+ pages ?

relevant technologies for the years >2025.

- break down in **work packages** 

- work plan with **deliverables**, **milestones**
- resources needs (CHF and FTE)
- risks, fall backs, alternatives
- have written a comprehensive report, describing
  - context and motivation
  - state of the art
  - main challenges
  - proposed R&D (as above)
  - outlook on further future
  - some ideas on management & reporting





## Some guidelines

- Some R&D themes are very obvious, others require discussions and prioritising (the resources will be limited)
- Process should be 'bottom-up' you are the experts! but some steering is needed
- Important: we don't want to miss clever non-conventional ideas
- We are defining an <u>EP</u> R&D programme, but we welcome and encourage the participation of external teams (see below)

# The process

Kick-off meeting

SG nominates convenors of 'obvious' WG

WG Conv. gather people and start to work 1 full day

R&D workshop I

**Open for external groups** 

 Proto-WGs and individuals present their ideas and proposals

→ Discuss and finalise list of WGs

WGs have meetings. Prepare their 'chapter'.

1-2 days

R&D workshop II

**Open for external groups** 

- WG present detailed plans
- Draft document available
- Harmonise work plan (common tasks, deliverables?)

Consolidation (resources)
Final editing / polishing

Release the document

SG = Steering Group WG = Working Group

#### Time line

Kick-off meeting

20 Nov 2017

R&D workshop I

Tentatively 16 March 2018

R&D workshop II

Early autumn 2018

Release the document

November 2018

## The steering group's prel. list of R&D themes

**Silicon Detectors**: Integrated CMOS, LGAD, packaging and high density interconnect (chip-to-chip, wafer-

to-wafer), tilable solutions

**Gas Detectors**: Micro pattern detectors, solutions for large areas, fast detectors, environment friendly

gases, technology transfer to industry

**Calorimetry:** Radiation hard technologies, timing ... ? How much EP involvement do / will we have ?

**Detector Integration**: Low-mass structures, cooling, microfabrication, composite technologies, robotics,

precision metrology and alignment

IC Technologies: Hybrid pixel detectors, increased functionalities on chips, very deep submicron

technologies, radiation hardness

**High speed Links**: Radiation hardness, power dissipation, silicon photonics, wireless solutions

**Software for Experiments**: New techniques for simulation and reconstruction, customizable turn-key systems, new

HW/SW technologies

**Detector Magnets**: Thin magnet technology?

We see potential for cooperation between the work packages. E.g. joint deliverables, common test beams, ...

#### Collaboration of external teams

- The program aims to support R&D activities in which EP teams play a major role.
- These activities shall fit in the global context. Cooperation with external teams is welcome, often essential.
- R&D collaborations, like RD50 and RD51, stimulate a huge resonance in the community, initiate and boost developments and foster communication and cooperation. They are LHCC reviewed.
- We expect that certain tasks of the new R&D program will be carried out (by EP personnel) inside these R&D collaborations. External teams may join in and in this way strengthen our program.